Session Title:	[TB1] Heterogeneous Integration Device and Packaging
Session Date:	November 21 (Tue.), 2023
Session Time:	08:30-10:10
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Prof. Gu-Sung Kim (Kangnam Univ., Korea)

[TB1-1] [Invited] 08:30-08:50

Supply Chain Trends, Challenges, and Disruptions in Semiconductor Packaging

Kitty Pearsall (IEEE EPS, USA)

[TB1-2] [Invited] 08:50-09:10

Solving High-Performance Packaging Challenges

E. Jan Vardaman (TechSearch International, Inc., USA)

[TB1-3] [Invited] 09:10-09:40

Advanced Packaging Technology for Heterogeneous Integration

Seok-Hyun Lee (Samsung Electronics Co., Ltd., Korea)

[TB1-4] [Invited] 09:40-10:10

Challenge Again for Latest Logic Semiconductor and Packaging Device

Takao Enomoto (Rapidus Corp. Inc., Japan)